

**BCN4D summary material content, BI Technologies Corporation 6/21/06**

Average mass of BCN4D array is 0.028 grams each. Scientific notation is used for all component masses.

<b>Homogeneous</b>					<b>Tolerance (% of</b>	
<b>Material Location</b>	<b>Homogeneous Material Name</b>	<b>Material name</b>	<b>CAS #</b>	<b>Weight per unit (grams)</b>	<b>homogenous material mass)</b>	<b>Special classification</b>
Substrate	Alumina	Aluminium trioxide	1344-28-1	2.455E-02	96.45%	
		Magnesium oxide	1309-48-4	2.830E-04	1.11%	
		Silicon dioxide	14808-60-7	5.320E-04	2.09%	
		Calcium oxide	1305-78-8	8.900E-05	0.35%	
Thick film	Metals and Oxides	Boron trioxide	1303-86-2	2.630E-04	12.45%	
		Bismuth trioxide	1304-76-3	1.400E-05	0.68%	
		Chromium(III) oxide	1308-38-9	2.200E-05	1.04%	
		Antimony trioxide	1309-64-4	1.000E-06	0.07%	
		Manganese(IV) oxide	1313-13-9	2.600E-05	1.25%	
		Zinc oxide	1314-13-2	1.100E-05	0.50%	
		Vanadium(V) oxide	1314-62-1	3.000E-06	0.14%	
		Lead(II) oxide	1317-36-8	7.560E-04	35.80%	PbO in thick film glass. Lead in glass of electronic components is exempted from RoHS Directive.
		Copper oxide	1317-38-0	2.900E-05	1.39%	
		Aluminium trioxide	1344-28-1	7.000E-05	3.30%	
		Ruthenium(IV) oxide	12036-10-1	4.600E-05	2.19%	
		Silicon dioxide	14808-60-7	2.660E-04	12.58%	
		Palladium	7440-05-3	3.700E-05	1.75%	
		Silver	7440-22-4	5.620E-04	26.63%	
rest		5.000E-06	0.23%	claimed as non-hazardous		
Termination	Plating	Nickel	7440-02-0	4.050E-04	55.00%	
		Tin	7440-31-5	3.310E-04	45.00%	